

POSITIVE-TYPE PHOTOSENSITIVE RESIN COMPOSITION

Abstract

Disclosed is a positive-type photosensitive resin composition which has excellent storage stability, particularly excellent sensitivity stability, and can be formed into a cured film having excellent adhesion onto a substrate when heated at 350°C or higher or heated in the air. The positive-type photosensitive resin composition comprises (a) a polymer having, as the main component, at least one structure selected from the group consisting of a polyimide precursor structure, a polybenzoxazole precursor structure, and a polyimide structure, (b) a quinonediazide compound, (c) a silane coupling agent having a styryl group, (d) a silane coupling agent having an epoxy group, an oxetanyl group, a methacryloxy group, an acryloxy group, an amino group, an amide group or mercapto group and an alkoxysilyl group, and (e) a solvent.

(No suitable figure)